



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20130903001**  
**Add Cu as Alternative Wire Base Metal for Selected Device(s)**  
**Change Notification / Sample Request**

**Date:** 9/6/2013  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services  
Phone: +1(214) 480-6037  
Fax: +1(214) 480-6659

**20130903001**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TMP75AID	null
TMP75AIDG4	null
TMP75AIDR	null
TMP75AIDRG4	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20130903001			<b>PCN Date:</b>	09/06/2013
<b>Title:</b>	Add Cu as Alternative Wire Base Metal for Selected Device(s)				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	12/06/2013	<b>Estimated Sample Availability:</b>	Date provided at sample request		
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>	Part number change			
<b>PCN Details</b>					
<b>Description of Change:</b>					
<p>Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and assembly differences are as follows:</p>					
<b>Group 1 Device:</b>					
	<b>Current Assembly</b>		<b>Bond wire option</b>		
Wire type	Au wire		Cu wire		
<b>Group 2 Device:</b>					
	<b>Current Assembly</b>		<b>Alternate Assembly</b>		
Wire type	Au		Cu		
Leadframe thickness	8mils		6mils		
Mold compound	4205694		4211880		
<b>Reason for Change:</b>					
<p>Continuity of supply.</p> <ol style="list-style-type: none"> <li>1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties</li> <li>2) Maximize flexibility within our Assembly/Test production sites.</li> <li>3) Cu is easier to obtain and stock</li> </ol>					

<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
None.			
<b>Changes to product identification resulting from this PCN:</b>			
None.			
<b>Product Affected: Group 1</b>			
TPS65149RSHR			
<b>Product Affected: Group 2</b>			
TMP75AID	TMP75AIDG4	TMP75AIDR	TMP75AIDRG4

<b>Qualification Data : Group 1</b>				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
<b>Qual Vehicle 1: TPS65149RSH (MSL 3-260C)</b>				
<b>Package Construction Details</b>				
Assembly Site:	CRS	Mold Compound:	435370	
# Pins-Designator, Family:	56-RSH, QFN	Mount Compound:	435143	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3Mil Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot #1	Lot #2	Lot #3
Electrical Characterization	-	Pass	-	-
**Autoclave	121C, 2atm (168hrs)	82/0	82/0	82/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	82/0	81/0	82/0
**High Temp. Storage Bake	150C (1000 hrs)	82/0	82/0	82/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes    ** - Preconditioning sequence: Level 3-260C.				

<b>Qualification Data : Group 2</b>					
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
<b>Qual Vehicle 1: OPA-2364ID (MSL 2-260C)</b>					
<b>Package Construction Details</b>					
Assembly Site:	MLA	Mold Compound:	4211880		
# Pins-Designator, Family:	8-D, SOIC	Mount Compound:	4042500		
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96Mil Cu		
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fail			
		Lot#1	Lot#2	Lot#3	
**Autoclave	121C, 2atm (96hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes    ** - Preconditioning sequence: Level 2-260C.					
<b>Qual Vehicle 2: SN0910049DR (MSL 2-260C)</b>					
<b>Package Construction Details</b>					
Assembly Site:	MLA	Mold Compound:	4211880		
# Pins-Designator, Family:	16-D, SOIC	Mount Compound:	4042500		
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96Mil Cu		
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fail			
		Lot#1	Lot#2	Lot#3	
**Autoclave	121C, 2atm (96hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes    ** - Preconditioning sequence: Level 2-260C.					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>